

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT5289672

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MARK MACDONALD	12/10/2018
DAVID PIDWERBECKI	12/12/2018
MARK GALLINA	12/12/2018
JERROD PETERSON	12/06/2018
RECEIVING PARTY DATA	
Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BOULEVARD
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16222854
CORRESPONDENCE DATA	
Fax Number:	(603)218-6622
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	5203396522
Email:	ipadmin@gtp.com
Correspondent Name:	GROSSMAN TUCKER PERREAULT & PFLEGER P
Address Line 1:	7660 E. BROADWAY BLVD, SUITE 207
Address Line 4:	TUCSON, ARIZONA 85710
ATTORNEY DOCKET NUMBER:	AB0808-US
NAME OF SUBMITTER:	EDMUND P. PFLEGER
SIGNATURE:	/Edmund P. Pflieger/
DATE SIGNED:	12/18/2018
Total Attachments: 6	
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ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

MARK MACDONALD
DAVID PIDWERBECKI
MARK GALLINA
JERROD PETERSON

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

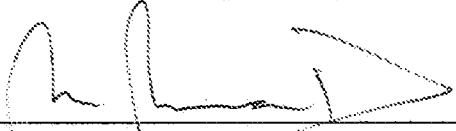
**ENHANCED SYSTEMS AND METHODS FOR IMPROVED HEAT TRANSFER
FROM SEMICONDUCTOR PACKAGES**

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed onDecember 17, 2018..... as
..... US Patent Application Number 16222854 and
..... COUNTRY or International Office

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below, and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements; and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications

on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



MARK MACDONALD

12/10/15

Date signed

DAVID PIDWERBECKI

Date signed

MARK GALLINA

Date signed

JERROD PETERSON

Date signed

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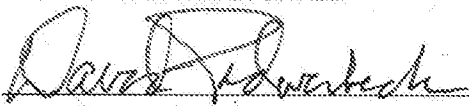
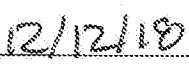
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_____ MARK GALLINA	_____ Date signed
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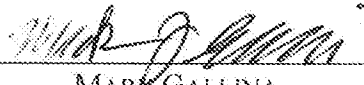
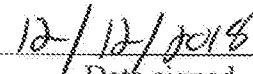

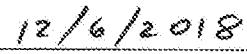
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